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#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	20MHz
Connectivity	SMBus (2-Wire/I²C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f000

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### 1. SYSTEM OVERVIEW

The C8051F000 family are fully integrated mixed-signal System on a Chip MCUs with a true 12-bit multi-channel ADC (F000/01/02/05/06/07), or a true 10-bit multi-channel ADC (F010/11/12/15/16/17). See the Product Selection Guide in Table 1.1 for a quick reference of each MCUs' feature set. Each has a programmable gain pre-amplifier, two 12-bit DACs, two voltage comparators (except for the F002/07/12/17, which have one), a voltage reference, and an 8051-compatible microcontroller core with 32kbytes of FLASH memory. There are also I2C/SMBus, UART, and SPI serial interfaces implemented in hardware (not "bit-banged" in user software) as well as a Programmable Counter/Timer Array (PCA) with five capture/compare modules. There are also 4 general-purpose 16-bit timers and 4 byte-wide general-purpose digital Port I/O. The C8051F000/01/02/10/11/12 have 256 bytes of RAM and execute up to 20MIPS, while the C8051F005/06/07/15/16/17 have 2304 bytes of RAM and execute up to 25MIPS.

With an on-board VDD monitor, WDT, and clock oscillator, the MCUs are truly stand-alone System-on-a-Chip solutions. Each MCU effectively configures and manages the analog and digital peripherals. The FLASH memory can be reprogrammed even in-circuit, providing non-volatile data storage, and also allowing field upgrades of the 8051 firmware. Each MCU can also individually shut down any or all of the peripherals to conserve power.

On-board JTAG debug support allows non-intrusive (uses no on-chip resources), full speed, in-circuit debug using the production MCU installed in the final application. This debug system supports inspection and modification of memory and registers, setting breakpoints, watchpoints, single stepping, and run and halt commands. All analog and digital peripherals are fully functional when using JTAG debug.

Each MCU is specified for 2.7V-to-3.6V operation over the industrial temperature range (-45C to +85C). The Port I/Os, /RST, and JTAG pins are tolerant for input signals up to 5V. The C8051F000/05/10/15 are available in the 64-pin TQFP (see block diagram in Figure 1.1). The C8051F001/06/11/16 are available in the 48-pin TQFP (see block diagram in Figure 1.2). The C8051F002/07/12/17 are available in the 32-pin LQFP (see block diagram in Figure 1.3).

	MIPS (Peak)	FLASH Memory	RAM	SMBus/I2C	IdS	UART	Timers (16-bit)	Programmable Counter Array	Digital Port I/O's	ADC Resolution (bits)	ADC Max Speed (ksps)	ADC Inputs	Voltage Reference	Temperature Sensor	DAC Resolution	DAC Outputs	Voltage Comparators	Package
C8051F000	20	32k	256	$\checkmark$	$\checkmark$	$\checkmark$	4	$\checkmark$	32	12	100	8	$\checkmark$	$\checkmark$	12	2	2	64TQFP
C8051F001	20	32k	256	$\checkmark$	$\checkmark$	$\checkmark$	4	$\checkmark$	16	12	100	8	$\checkmark$	$\checkmark$	12	2	2	48TQFP
C8051F002	20	32k	256	$\checkmark$	$\checkmark$	$\checkmark$	4	$\checkmark$	8	12	100	4	$\checkmark$	$\checkmark$	12	2	1	32LQFP
C8051F005	25	32k	2304		$\checkmark$	$\checkmark$	4	$\checkmark$	32	12	100	8	$\checkmark$	$\checkmark$	12	2	2	64TQFP
C8051F006	25	32k	2304		$\checkmark$	$\checkmark$	4		16	12	100	8	$\checkmark$	$\checkmark$	12	2	2	48TQFP
C8051F007	25	32k	2304		$\checkmark$	$\checkmark$	4	$\checkmark$	8	12	100	4	$\checkmark$	$\checkmark$	12	2	1	32LQFP
C8051F010	20	32k	256		$\checkmark$	$\checkmark$	4	$\checkmark$	32	10	100	8	$\checkmark$	$\checkmark$	12	2	2	64TQFP
C8051F011	20	32k	256	$\checkmark$	$\checkmark$	$\checkmark$	4	$\checkmark$	16	10	100	8	$\checkmark$	$\checkmark$	12	2	2	48TQFP
C8051F012	20	32k	256				4		8	10	100	4	$\checkmark$	$\checkmark$	12	2	1	32LQFP
C8051F015	25	32k	2304		$\checkmark$	$\checkmark$	4	$\checkmark$	32	10	100	8	$\checkmark$	$\checkmark$	12	2	2	64TQFP
C8051F016	25	32k	2304		$\checkmark$	$\checkmark$	4	$\checkmark$	16	10	100	8	$\checkmark$	$\checkmark$	12	2	2	48TQFP
C8051F017	25	32k	2304		$\checkmark$	$\checkmark$	4	$\checkmark$	8	10	100	4	$\checkmark$	$\checkmark$	12	2	1	32LQFP

 Table 1.1. Product Selection Guide





Figure 1.2. C8051F001/06/11/16 Block Diagram



#### **1.1.3.** Additional Features

The C8051F000 MCU family has several key enhancements both inside and outside the CIP-51 core to improve its overall performance and ease of use in the end applications.

The extended interrupt handler provides 21 interrupt sources into the CIP-51 (as opposed to 7 for the standard 8051), allowing the numerous analog and digital peripherals to interrupt the controller. An interrupt driven system requires less intervention by the MCU, giving it more effective throughput. The extra interrupt sources are very useful when building multi-tasking, real-time systems.

There are up to seven reset sources for the MCU: an on-board VDD monitor, a Watchdog Timer, a missing clock detector, a voltage level detection from Comparator 0, a forced software reset, the CNVSTR pin, and the /RST pin. The /RST pin is bi-directional, accommodating an external reset, or allowing the internally generated POR to be output on the /RST pin. Each reset source except for the VDD monitor and Reset Input Pin may be disabled by the user in software. The WDT may be permanently enabled in software after a power-on reset during MCU initialization.

The MCU has an internal, stand alone clock generator which is used by default as the system clock after any reset. If desired, the clock source may be switched on the fly to the external oscillator, which can use a crystal, ceramic resonator, capacitor, RC, or external clock source to generate the system clock. This can be extremely useful in low power applications, allowing the MCU to run from a slow (power saving) external crystal source, while periodically switching to the fast (up to 16MHz) internal oscillator as needed.



Figure 1.5. On-Board Clock and Reset



### 1.3. JTAG Debug and Boundary Scan

The C8051F000 family has on-chip JTAG and debug circuitry that provide *non-intrusive, full speed, in-circuit debug using the production part installed in the end application* using the four-pin JTAG I/F. The JTAG port is fully compliant to IEEE 1149.1, providing full boundary scan for test and manufacturing purposes.

Silicon Labs' debug system supports inspection and modification of memory and registers, breakpoints, watchpoints, a stack monitor, and single stepping. No additional target RAM, program memory, timers, or communications channels are required. All the digital and analog peripherals are functional and work correctly while debugging. All the peripherals (except for the ADC) are stalled when the MCU is halted, during single stepping, or at a breakpoint in order to keep them in sync.

The C8051F000DK, C8051F005DK, C8051F010DK, and C8051F015DK are development kits with all the hardware and software necessary to develop application code and perform in-circuit debug with the C8051F000/1/2, F005/6/7, F010/1/2, and F015/6/7 MCUs respectively. The kit includes software with a developer's studio and debugger, an integrated 8051 assembler, and an RS-232 to JTAG protocol translator module referred to as the EC. It also has a target application board with the associated MCU installed and a large prototyping area, plus the RS-232 and JTAG cables, and wall-mount power supply. The Development Kit requires a Windows 95/98/NT/2000/XP computer with one available RS-232 serial port. As shown in Figure 1.7, the PC is connected via RS-232 to the EC. A six-inch ribbon cable connects the EC to the user's application board, picking up the four JTAG pins and VDD and GND. The EC takes its power from the application board. It requires roughly 20mA at 2.7-3.6V. For applications where there is not sufficient power available from the target board, the provided power supply can be connected directly to the EC.

This is a vastly superior configuration for developing and debugging embedded applications compared to standard MCU Emulators, which use on-board "ICE Chips" and target cables and require the MCU in the application board to be socketed. Silicon Labs' debug environment both increases ease of use and preserves the performance of the precision analog peripherals.







### **1.7.** Analog to Digital Converter

The C8051F000/1/2/5/6/7 has an on-chip 12-bit SAR ADC with a 9-channel input multiplexer and programmable gain amplifier. With a maximum throughput of 100ksps, the ADC offers true 12-bit accuracy with an INL of  $\pm$ 1LSB. The ADC in the C8051F010/1/2/5/6/7 is similar, but with 10-bit resolution. Each ADC has a maximum throughput of 100ksps. Each ADC has an INL of  $\pm$ 1LSB, offering true 12-bit accuracy with the C8051F00x, and true 10-bit accuracy with the C8051F01x. There is also an on-board 15ppm voltage reference, or an external reference may be used via the VREF pin.

The ADC is under full control of the CIP-51 microcontroller via the Special Function Registers. One input channel is tied to an internal temperature sensor, while the other eight channels are available externally. Each pair of the eight external input channels can be configured as either two single-ended inputs or a single differential input. The system controller can also put the ADC into shutdown to save power.

A programmable gain amplifier follows the analog multiplexer. The gain can be set in software from 0.5 to 16 in powers of 2. The gain stage can be especially useful when different ADC input channels have widely varied input voltage signals, or when it is necessary to "zoom in" on a signal with a large DC offset (in differential mode, a DAC could be used to provide the DC offset).

Conversions can be started in four ways; a software command, an overflow on Timer 2, an overflow on Timer 3, or an external signal input. This flexibility allows the start of conversion to be triggered by software events, external HW signals, or convert continuously. A completed conversion causes an interrupt, or a status bit can be polled in software to determine the end of conversion. The resulting 10 or 12-bit data word is latched into two SFRs upon completion of a conversion. The data can be right or left justified in these registers under software control.

Compare registers for the ADC data can be configured to interrupt the controller when ADC data is within a specified window. The ADC can monitor a key voltage continuously in background mode, but not interrupt the controller unless the converted data is within the specified window.



#### Figure 1.10. ADC Diagram



### 2. ABSOLUTE MAXIMUM RATINGS\*

Ambient temperature under bias	
Storage Temperature	65 to 150°C
Voltage on any Pin (except VDD and Port I/O) with respect to DGND	$-0.3V$ to (VDD + 0.3V)
Voltage on any Port I/O Pin or /RST with respect to DGND	0.3V to 5.8V
Voltage on VDD with respect to DGND	0.3V to 4.2V
Maximum Total current through VDD, AV+, DGND and AGND	
Maximum output current sunk by any Port pin	
Maximum output current sunk by any other I/O pin	25mA
Maximum output current sourced by any Port pin	100mA
Maximum output current sourced by any other I/O pin	25mA

\*Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

### 3. GLOBAL DC ELECTRICAL CHARACTERISTICS

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Analog Supply Voltage	(Note 1)	2.7	3.0	3.6	V
Analog Supply Current	Internal REF, ADC, DAC, Comparators		1	2	mA
	all active				
Analog Supply Current with	Internal REF, ADC, DAC, Comparators		5	20	μA
analog sub-systems inactive	all disabled, oscillator disabled				
Analog-to-Digital Supply				0.5	V
Delta ( $ VDD - AV +  $ )					
Digital Supply Voltage		2.7	3.0	3.6	V
Digital Supply Current with	VDD = 2.7V, Clock=25MHz		12.5		mA
CPU active	VDD = 2.7V, Clock=1MHz		0.5		mA
	VDD = 2.7V, Clock=32kHz		10		μΑ
Digital Supply Current	Oscillator not running		5		μA
(shutdown)					
Digital Supply RAM Data			1.5		V
Retention Voltage					
Specified Operating		-40		+85	°C
Temperature Range					
SYSCLK (System Clock	C8051F005/6/7, C8051F015/6/7	0		25	MHz
Frequency)	(Note 2)				
SYSCLK (System Clock	C8051F000/1/2, C8051F010/1/2	0		20	MHz
Frequency)	(Note 2)				
Tsysl (SYSCLK Low Time)		18			ns
Tsysh (SYSCLK High Time)		18			ns

-40°C to +85°C unless otherwise specified.

Note 1: Analog Supply AV+ must be greater than 1V for VDD monitor to operate. Note 2: SYSCLK must be at least 32 kHz to enable debugging.





Figure 5.4. AMX0CF: AMUX Configuration Register (C8051F00x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
-	-	-	- AIN67IC AIN45IC AIN23IC AIN01IC 0								
Bit7	Bit6	Bit6 Bit5 Bit4 Bit3 Bit2 Bit1 Bit0 SFR									
								0xBA			
Bits7-4	UNUSED. Rea	d = 0000b; V	Vrite = don't	care							
Bit3:	AIN67IC: AIN6	5. AIN7 Inpu	t Pair Config	uration Bit							
	0: AIN6 and A	N7 are inder	pendent singl	ed-ended inn	uts						
	$1 \cdot AIN6 AIN7$	are (respecti	velv) + - dif	ferential inpu	ut pair						
Bit2.	AIN45IC · AIN4	L AIN5 Inpu	t Pair Config	uration Bit	n puii						
D1(2)	0 AIN4 and Al	N5 are inder	endent singl	ed-ended inn	uts						
	1. $\Lambda$ IN/4 $\Lambda$ IN/5	are (respecti	$v_{alv} \perp dif$	forential input	uto it pair						
Dit1.	AIN22IC: AIN2	AIN3 Inpu	t Dair Config	uration Bit	n pan						
DITI.	AIN25IC. AIN2	N2 are inder	t Fair Coinig	ad and ad inn	uto						
	$\begin{array}{c} 0.  \text{AIN2}  \text{and}  \text{AIN2} \\ 1.  \text{AIN2}  \text{AIN2} \end{array}$	and (machine)	volu) - dif	formatical input	uis						
D:40	1: AIN2, AIN3	are (respecti	very) +, - dil	ierential inpl	it pair						
B1t0:	AINUTIC: AINU	), AINT Inpu	t Pair Config	uration Bit							
	0: AINO and A	INI are indep	pendent singl	ed-ended inp	uts						
	1: AIN0, AIN1	are (respecti	vely) +, - dif	ferential inpu	it pair						
NOTE.	The ADC Date V	Word is in 2'		t format for	honnala oon	figured og dif	Formatio				
NOTE:	The ADC Data	word is in 2	s complemen	it format for (	channels con	ingured as dif	Terential.				







Figure 6.4. AMX0CF: AMUX Configuration Register (C8051F01x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
-	-	-	- AIN67IC AIN45IC AIN23IC AIN01IC 0								
Bit7	Bit6	Bit6 Bit5 Bit4 Bit3 Bit2 Bit1 Bit0 SI									
Bits7-4:	UNUSED. Rea	d = 0000b; V	Vrite = don't	care							
Bit3:	AIN67IC: AIN6	5, AIN7 Inpu	t Pair Config	uration Bit							
	0: AIN6 and Al	N7 are inde	pendent singl	ed-ended inp	uts						
	1: AIN6. AIN7	are (respecti	velv) + dif	ferential inpu	t pair						
Bit2:	AIN45IC: AIN4	. AIN5 Inpu	t Pair Config	uration Bit	o puil						
2	0: AIN4 and Al	N5 are inder	pendent singl	ed-ended inp	uts						
	$1 \cdot AIN4 AIN5$	are (respecti	velv) + - dif	ferential inpu	ut nair						
Bit1.	AIN23IC · AIN2	AIN3 Inpu	t Pair Config	uration Bit	n pull						
DR1.	0: AIN2 and Al	N3 are inder	endent singl	ed-ended inn	uts						
	$1 \cdot \Delta IN2 \Delta IN3$	are (respecti	$velv) \perp - dif$	ferential inpu	ut nair						
BitO	AINOLIC: AINO	) AIN1 Inpu	t Pair Config	uration Bit	n pan						
Dito.	0. AINO and Al	N1 ara inda	ondont singl	ad and ad inn	ute						
	1. AINO AINI		volv) – dif	formatical input	uis						
	1: AINO, AINT	are (respecti	very) +, - dif	ierentiai inpu	n pair						
NOTE	The ADC Dete V	Word is in ?	a aomnlaman	t format for	hannala com	figurad as dif	fformatio				
NOTE:	The ADC Data	word is in 2	s complemen	it format for (	channels con	ingured as dil	lierential.				



### Figure 6.15. 10-Bit ADC Window Interrupt Examples, Left Justified Data





Mnemonic	Description	Bytes	Clock Cycles
RR A	Rotate A right	1	1
RRC A	Rotate A right through carry	1	1
SWAP A	Swap nibbles of A	1	1
	DATA TRANSFER		
MOV A,Rn	Move register to A	1	1
MOV A, direct	Move direct byte to A	2	2
MOV A,@Ri	Move indirect RAM to A	1	2
MOV A,#data	Move immediate to A	2	2
MOV Rn,A	Move A to register	1	1
MOV Rn,direct	Move direct byte to register	2	2
MOV Rn,#data	Move immediate to register	2	2
MOV direct,A	Move A to direct byte	2	2
MOV direct,Rn	Move register to direct byte	2	2
MOV direct, direct	Move direct byte to direct	3	3
MOV direct,@Ri	Move indirect RAM to direct byte	2	2
MOV direct,#data	Move immediate to direct byte	3	3
MOV @Ri,A	Move A to indirect RAM	1	2
MOV @Ri,direct	Move direct byte to indirect RAM	2	2
MOV @Ri,#data	Move immediate to indirect RAM	2	2
MOV DPTR,#data16	Load data pointer with 16-bit constant	3	3
MOVC A,@A+DPTR	Move code byte relative DPTR to A	1	3
MOVC A.@A+PC	Move code byte relative PC to A	1	3
MOVX A.@Ri	Move external data (8-bit address) to A	1	3
MOVX @Ri.A	Move A to external data (8-bit address)	1	3
MOVX A.@DPTR	Move external data (16-bit address) to A	1	3
MOVX @DPTR,A	Move A to external data (16-bit address)	1	3
PUSH direct	Push direct byte onto stack	2	2
POP direct	Pop direct byte from stack	2	2
XCH A.Rn	Exchange register with A	1	1
XCH A.direct	Exchange direct byte with A	2	2
XCH A.@Ri	Exchange indirect RAM with A	1	2
XCHD A.@Ri	Exchange low nibble of indirect RAM with A	1	2
	BOOLEAN MANIPULATION		I
CLR C	Clear carry	1	1
CLR bit	Clear direct bit	2	2
SETB C	Set carry	1	1
SETB bit	Set direct bit	2	2
CPL C	Complement carry	1	1
CPL bit	Complement direct bit	2	2
ANL C,bit	AND direct bit to carry	2	2
ANL C,/bit	AND complement of direct bit to carry	2	2
ORL C,bit	OR direct bit to carry	2	2
ORL C,/bit	OR complement of direct bit to carry	2	2
MOV C,bit	Move direct bit to carry	2	2
MOV bit,C	Move carry to direct bit	2	2
JC rel	Jump if carry is set	2	2/3
JNC rel	Jump if carry not set	2	2/3
JB bit,rel	Jump if direct bit is set	3	3/4
JNB bit,rel	Jump if direct bit is not set	3	3/4
JBC bit,rel	Jump if direct bit is set and clear bit	3	3/4



#### **11.2.** Non-volatile Data Storage

The Flash memory can be used for non-volatile data storage as well as program code. This allows data such as calibration coefficients to be calculated and stored at run time. Data is written using the MOVX instruction and read using the MOVC instruction.

The MCU incorporates an additional 128-byte sector of Flash memory located at 0x8000 – 0x807F. This sector can be used for program code or data storage. However, its smaller sector size makes it particularly well suited as general purpose, non-volatile scratchpad memory. Even though Flash memory can be written a single byte at a time, an entire sector must be erased first. In order to change a single byte of a multi-byte data set, the data must be moved to temporary storage. Next, the sector is erased, the data set updated and the data set returned to the original sector. The 128-byte sector-size facilitates updating data without wasting program memory space by allowing the use of internal data RAM for temporary storage. (A normal 512-byte sector is too large to be stored in the 256-byte internal data memory.)

#### **11.3.** Security Options

The CIP-51 provides security options to protect the Flash memory from inadvertent modification by software as well as prevent the viewing of proprietary program code and constants. The Program Store Write Enable (PSCTL.0) and the Program Store Erase Enable (PSCTL.1) bits protect the Flash memory from accidental modification by software. These bits must be explicitly set to logic 1 before software can modify the Flash memory. Additional security features prevent proprietary program code and data constants from being read or altered across the JTAG interface or by software running on the system controller.

A set of security lock bytes stored at 0x7DFE and 0x7DFF protect the Flash program memory from being read or altered across the JTAG interface. Each bit in a security lock-byte protects one 4kbyte block of memory. Clearing a bit to logic 0 in a Read lock byte prevents the corresponding block of Flash memory from being read across the JTAG interface. Clearing a bit in the Write/Erase lock byte protects the block from JTAG erasures and/or writes. The Read lock byte is at location 0x7DFF. The Write/Erase lock byte is located at 0x7DFE. Figure 11.2 shows the location and bit definitions of the security bytes. The 512-byte sector containing the lock bytes can be written to, but not erased by software. Writing to the reserved area should not be performed.

R/W	R/W	R/W	R/W	R/W	R/W	R/W PSEE	R/W PSWF	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0x8F
Bits7-2	: UNUSED. Re	ead = 000000	b, Write = d	lon't care.				
Bit1:	PSEE: Program Setting this bit the PSWE bit instruction will instruction. Th 0: Flash progra 1: Flash program	m Store Eras allows an erais is also set. A l erase the erain he value of t am memory am memory	e Enable. ntire page of After setting ntire page tha he data byte erasure disab erasure enab	the Flash pro this bit, a writ at contains the written does n bled. led.	gram memo e to Flash m e location ad not matter.	ry to be erase temory using dressed by the	d provided the MOVX e MOVX	
Bit0:	PSWE: Progra Setting this bit MOVX instruct 0: Write to Fla 1: Write to Fla	am Store Writ a allows writi ction. The lo ash program ash program	ite Enable. ing a byte of ocation must memory disa memory enal	data to the Fl be erased bef bled. bled.	ash program ore writing o	a memory usir data.	ng the	



### **13. RESET SOURCES**

The reset circuitry of the MCUs allows the controller to be easily placed in a predefined default condition. On entry to this reset state, the CIP-51 halts program execution, forces the external port pins to a known state and initializes the SFRs to their defined reset values. Interrupts and timers are disabled. On exit, the program counter (PC) is reset, and program execution starts at location 0x0000.

All of the SFRs are reset to predefined values. The reset values of the SFR bits are defined in the SFR detailed descriptions. The contents of internal data memory are not changed during a reset and any previously stored data is preserved. However, since the stack pointer SFR is reset, the stack is effectively lost even though the data on the stack are not altered.

The I/O port latches are reset to 0xFF (all logic ones), activating internal weak pull-ups which take the external I/O pins to a high state. The weak pull-ups are enabled during and after the reset. If the source of reset is from the VDD Monitor or writing a 1 to PORSF, the /RST pin is driven low until the end of the VDD reset timeout.

On exit from the reset state, the MCU uses the internal oscillator running at 2MHz as the system clock by default. Refer to Section 14 for information on selecting and configuring the system clock source. The Watchdog Timer is enabled using its longest timeout interval. (Section 13.8 details the use of the Watchdog Timer.)

There are seven sources for putting the MCU into the reset state: power-on/power-fail, external /RST pin, external CNVSTR signal, software commanded, Comparator 0, Missing Clock Detector, and Watchdog Timer. Each reset source is described below:







### 17.2. Operation

Only a SPI master device can initiate a data transfer. The SPI is placed in master mode by setting the Master Enable flag (MSTEN, SPIOCN.1). Writing a byte of data to the SPI data register (SPIODAT) when in Master Mode starts a data transfer. The SPI master immediately shifts out the data serially on the MOSI line while providing the serial clock on SCK. The SPIF (SPIOCN.7) flag is set to logic 1 at the end of the transfer. If interrupts are enabled, an interrupt request is generated when the SPIF flag is set. The SPI master can be configured to shift in/out from one to eight bits in a transfer operation in order to accommodate slave devices with different word lengths. The SPIFRS bits in the SPI Configuration Register (SPIOCFG.[2:0]) are used to select the number of bits to shift in/out in a transfer operation.

While the SPI master transfers data to a slave on the MOSI line, the addressed SPI slave device simultaneously transfers the contents of its shift register to the SPI master on the MISO line in a full-duplex operation. The data byte received from the slave replaces the data in the master's data register. Therefore, the SPIF flag serves as both a transmit-complete and receive-data-ready flag. The data transfer in both directions is synchronized with the serial clock generated by the master. Figure 17.3 illustrates the full-duplex operation of an SPI master and an addressed slave.



Figure 17.3. Full Duplex Operation

The SPI data register is double buffered on reads, but not on a write. If a write to SPI0DAT is attempted during a data transfer, the WCOL flag (SPI0CN.6) will be set to logic 1 and the write is ignored. The current data transfer will continue uninterrupted. A read of the SPI data register by the system controller actually reads the receive buffer. If the receive buffer still holds unread data from a previous transfer when the last bit of the current transfer is shifted into the SPI shift register, a receive overrun occurs and the RXOVRN flag (SPI0CN.4) is set to logic 1. The new data is not transferred to the receive buffer, allowing the previously received data byte to be read. The data byte causing the overrun is lost.

When the SPI is enabled and not configured as a master, it will operate as an SPI slave. Another SPI device acting as a master will initiate a transfer by driving the NSS signal low. The master then shifts data out of the shift register on the MOSI pin using the its serial clock. The SPIF flag is set to logic 1 at the end of a data transfer (when the NSS signal goes high). The slave can load its shift register for the next data transfer by writing to the SPI data register. The slave must make the write to the data register at least one SPI serial clock cycle before the master starts the next transmission. Otherwise, the byte of data already in the slave's shift register will be transferred.

Multiple masters may reside on the same bus. A Mode Fault flag (MODF, SPI0CN.5) is set to logic 1 when the SPI is configured as a master (MSTEN = 1) and its slave select signal NSS is pulled low. When the Mode Fault flag is set, the MSTEN and SPIEN bits of the SPI control register are cleared by hardware, thereby placing the SPI module



Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is 0 or the input signal /INT0 is logic-level one. Setting GATE0 to logic 1 allows the timer to be controlled by the external input signal /INT0, facilitating pulse width measurements.

TR0	GATE0	/INT0	<b>Counter/Timer</b>					
0	X	Х	Disabled					
1	0	Х	Enabled					
1	1	0	Disabled					
1	1	1	Enabled					
X = D	X = Don't Care							

Setting TR0 does not reset the timer register. The timer register should be initialized to the desired value before enabling the timer.

TL1 and TH1 form the 13-bit register for Timer 1 in the same manner as described above for TL0 and TH0. Timer 1 is configured and controlled using the relevant TCON and TMOD bits just as with Timer 0.



Figure 19.1. T0 Mode 0 Block Diagram

#### 19.1.2. Mode 1: 16-bit Counter/Timer

Mode 1 operation is the same as Mode 0, except that the counter/timer registers use all 16 bits. The counter/timers are enabled and configured in Mode 1 in the same manner as for Mode 0.



#### 19.1.4. Mode 3: Two 8-bit Counter/Timers (Timer 0 Only)

Timer 0 and Timer 1 behave differently in Mode 3. Timer 0 is configured as two separate 8-bit counter/timers held in TL0 and TH0. The counter/timer in TL0 is controlled using the Timer 0 control/status bits in TCON and TMOD: TR0, C/T0, GATE0 and TF0. It can use either the system clock or an external input signal as its timebase. The TH0 register is restricted to a timer function sourced by the system clock. TH0 is enabled using the Timer 1 run control bit TR1. TH0 sets the Timer 1 overflow flag TF1 on overflow and thus controls the Timer 1 interrupt.

Timer 1 is inactive in Mode 3, so with Timer 0 in Mode 3, Timer 1 can be turned off and on by switching it into and out of its Mode 3. When Timer 0 is in Mode 3, Timer 1 can be operated in Modes 0, 1 or 2, but cannot be clocked by external signals nor set the TF1 flag and generate an interrupt. However, the Timer 1 overflow can be used for baud rate generation. Refer to Section 18 (UART) for information on configuring Timer 1 for baud rate generation.



Figure 19.3. T0 Mode 3 Block Diagram



#### 20.1. Capture/Compare Modules

Each module can be configured to operate independently in one of four operation modes: Edge-triggered Capture, Software Timer, High Speed Output, or Pulse Width Modulator. Each module has Special Function Registers (SFRs) associated with it in the CIP-51 system controller. These registers are used to exchange data with a module and configure the module's mode of operation.

Table 20.1 summarizes the bit settings in the PCA0CPMn registers used to place the PCA capture/compare modules into different operating modes. Setting the ECCFn bit in a PCA0CPMn register enables the module's CCFn interrupt. Note: PCA0 interrupts must be globally enabled before individual CCFn interrupts are recognized. PCA0 interrupts are globally enabled by setting the EA bit (IE.7) and the EPCA0 bit (EIE1.3) to logic 1. See Figure 20.2 for details on the PCA interrupt configuration.

				-	-		
ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	Operation Mode
Х	1	0	0	0	0	Х	Capture triggered by positive edge on CEXn
Х	0	1	0	0	0	Х	Capture triggered by negative edge on

0

0

0

1

Х

Х

Х

Х

0

1

1

Х

0

0

1

0

Table 20.1	PCA0CPM Register	Settings for PCA	Canture/Compare	Modules
1 auto 20.1.	I CAUCI INI INERISICI	Schungs for I CA	Captul C/Compare	

X = Don't Care

1

0

0

0

1

0

0

0

Х

1

1

1







Capture triggered by transition on CEXn

Software Timer

High Speed Output

Pulse Width Modulator

155

#### 20.1.4. Pulse Width Modulator Mode

All of the modules can be used independently to generate pulse width modulated (PWM) outputs on their respective CEXn pin. The frequency of the output is dependent on the timebase for the PCA counter/timer. The duty cycle of the PWM output signal is varied using the module's PCA0CPLn capture/compare register. When the value in the low byte of the PCA counter/timer (PCA0L) is equal to the value in PCA0CPLn, the output on the CEXn pin will be set. When the count value in PCA0L overflows, the CEXn output will be reset (see Figure 20.6). Also, when the counter/timer low byte (PCA0L) overflows from 0xFF to 0x00, PCA0CPLn is reloaded automatically with the value stored in the PCA0CPHn without software intervention. It is good practice to write to PCA0CPHn instead of PCA0CPLn to avoid glitches in the digital comparator. Setting the ECOMn and PWMn bits in the PCA0CPMn register enables Pulse Width Modulator mode.







R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	ECOMn	CAPPn	CAPNn	MATn	TOGn	PWMn	ECCFn	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xDA-0xDE
PCA0C	CPMn Address:	PCA0CPM	10 = 0 xDA (n)	( = 0 )				
		PCA0CPM	[1 = 0xDB (n	= 1)				
		PCA0CPM	12 = 0 xDC (n)	= 2)				
		PCA0CPM	13 = 0 xDD (n)	1 = 3)				
		PCA0CPM	4 = 0 xDE (n)	= 4)				
D:+7.	UNUSED D	ad - 0 Writ	a - dan't aar					
DIL/. Bit6:	ECOMp: Com	au = 0, with	e = uon t can	е.				
Dito.	This bit enable	parator Fund	e comparato	r function for	PCA modul	0 11		
	0. Disabled	25/disables th	ie comparato	i function foi	I CA IIIouui	с п.		
	1. Enabled							
Bit5:	CAPPn: Captu	re Positive F	Function Ena	ble.				
	This bit enable	es/disables th	e positive ed	ge capture fo	r PCA modu	le n.		
	0: Disabled.		1	0 1				
	1: Enabled.							
Bit4:	CAPNn: Capt	ure Negative	Function En	able.				
	This bit enable	es/disables th	e negative ed	lge capture f	or PCA modu	ıle <i>n</i> .		
	0: Disabled.							
	1: Enabled.							
Bit3:	MATn: Match	Function Er	nable.					_
	This bit enable	es/disables th	e match func	tion for PCA	module n.	When enabled	1, matches of	
	the PCA coun	ter with a mo	odule's captu	re/compare re	egister cause	the CCFn bit	in	
	PCA0MD register to be set.							
	0: Disabled.							
Bit?	TOGn: Toggle	Eurotion F	nabla					
DIL2.	This bit enable	es/disables th	naule. Ne toggle fund	tion for PCA	module <i>n</i>	When enable	d matches	
	of the PCA counter with a module's capture/compare register cause the logic level on the CEXn pin to toggle.							
	0: Disabled.	- 88						
	1: Enabled.							
Bit1:	PWMn: Pulse	Width Modu	ulation Mode	Enable.				
	This bit enable	es/disables th	e comparato	r function for	PCA modul	e n. When er	nabled, a	
	pulse width m	odulated sign	nal is output o	on the CEXn	pin.			
	0: Disabled.							
<b>D</b> .	1: Enabled.	10						
Bit0:	ECCFn: Captu	ire/Compare	Flag Interrup	ot Enable.				
	This bit sets the	e masking o	t the Capture	Compare Fl	ag (CCFn) in	terrupt.		
	1: Enchlar C	onturo/Comm	s. Joro Flog into	rrunt request	when CCE-	is sot		
		apture/Comp	are mag inte	mupi request		15 501.		

### Figure 20.10. PCA0CPMn: PCA Capture/Compare Registers



#### 21.2. Flash Programming Commands

The Flash memory can be programmed directly over the JTAG interface using the Flash Control, Flash Data, Flash Address, and Flash Scale registers. These Indirect Data Registers are accessed via the JTAG Instruction Register. Read and write operations on indirect data registers are performed by first setting the appropriate DR address in the IR register. Each read or write is then initiated by writing the appropriate Indirect Operation Code (IndOpCode) to the selected data register. Incoming commands to this register have the following format:

19:18	17:0	
IndOpCode	WriteData	

IndOpCode: These bit set the operation to perform according to the following table:

IndOpCode	Operation
0x	Poll
10	Read
11	Write

The Poll operation is used to check the Busy bit as described below. Although a Capture-DR is performed, no Update-DR is allowed for the Poll operation. Since updates are disabled, polling can be accomplished by shifting in/out a single bit.

The Read operation initiates a read from the register addressed by the IR. Reads can be initiated by shifting only 2 bits into the indirect register. After the read operation is initiated, polling of the Busy bit must be performed to determine when the operation is complete.

The write operation initiates a write of WriteData to the register addressed by the IR. Registers of any width up to 18 bits can be written. If the register to be written contains fewer than 18 bits, the data in WriteData should be left-justified, i.e. its MSB should occupy bit 17 above. This allows shorter registers to be written in fewer JTAG clock cycles. For example, an 8-bit register could be written by shifting only 10 bits. After a Write is initiated, the Busy bit should be polled to determine when the next operation can be initiated. The contents of the Instruction Register should not be altered while either a read or write operation is in progress.

Outgoing data from the indirect Data Register has the following format:

19	18:1	0
0	ReadData	Busy

The Busy bit indicates that the current operation is not complete. It goes high when an operation is initiated and returns low when complete. Read and Write commands are ignored while Busy is high. In fact, if polling for Busy to be low will be followed by another read or write operation, JTAG writes of the next operation can be made while checking for Busy to be low. They will be ignored until Busy is read low, at which time the new operation will initiate. This bit is placed at bit 0 to allow polling by single-bit shifts. When waiting for a Read to complete and Busy is 0, the following 18 bits can be shifted out to obtain the resulting data. ReadData is always right-justified. This allows registers shorter than 18 bits to be read using a reduced number of shifts. For example, the result from a byte-read requires 9 bit shifts (Busy + 8 bits).

